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Need for Improved Validation Process of New Test Infrastructure

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Introduction

The test user community utilizes many methods to validate new test cell performance:

- Blind trust of vendor diagnostics.
- Run a handful of specific qualification devices.
- Run every known device application.
- Create and run process corner devices.
- Create and run specific applications to test instrument specification corners.
- Create and run specific applications to test system performance and reliability.
- Perform some combination of the above.

Test Cell Integration Validation Traditional Method

Vendor
diagnostics

Intent Verify equipment performance specification
Gap Diagnostic mode v/s Application mode differences

Identify a pilot
'qualification'
device

Intent Application mode verification
Gap Device use case limited coverage

Perform
correlation
exercise on pilot
device

Intent Validate accuracy and sameness
Gap Device specific baseline data (arbitrary reference)

RTP or Learning Cycle (LC)



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New Validation Motivation | Why evolve?

- Problem Statement:
 - Traditional methods cause revenue loss in the volume ramp phase driven by problem identification and resolution.
- Issues seen from traditional process:
 - **Device (typically new technology) availability** delays
 - Device release to production (RTP) dependent on 1st pass, **no learning cycle** margin
 - Coverage gaps
 - **Missed** operational **corners**
 - **Post qualification tool updates**
 - Reliability **issues during production**
 - **Increased cost** of maintenance
 - Increased **total cost ownership**

Failure	Root-Cause	Major Action	Who
Full Board device fails	Bad / Loose connection between TEB and PEB due to vibration	Vendor provide seismic mounts and install instructions to factory	Vendor
Incomplete Run	Step Time-Out TEB ECC VGEN Error	Fix with Firmware	Vendor
Heater Wire Reliability Issues	Heater wire too long causing contact with BIB	Vendor reduce wire length and tighten length tolerance	Vendor
Device not reaching required T_j	Inconsistent BIB airflow and over-efficient heatsink	Install airfoils for BIBs	Factory
Stuck pins because the spring melted into the plastic	High transition current between steps	Fix with Firmware	Vendor

BI Losses Through A System Ramp

- Test Cell validation evolution is desired to fully understand the system **performance** ahead of large scale deployment thereby avoiding costly issues while testing across a **range of devices, fab processes, and/or factory requirements.**



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Example Gaps | Underqualified BI Systems

Historical Issue	Impact	Detectability	
		Pilot Device Qual	Evolved Validation
Airflow non-uniformity causes heating/cooling issues during high-power burn-in.	Lost burn-in capacity	NO	YES
Excessive ripple when some high voltage supplies run at low end of capable range.	Burn-in test instability	NOT COMPREHENSIVE	YES
Insufficient driver cabinet cooling when all slots run at high load.	Oven down-time increased	NOT COMPREHENSIVE	YES (full oven-worth HW needed)
Inaccurate and drifting output voltage when 5v supply set to max setpoint (5.00v).	Device temperature controller resets; failed burn-in runs	NO	YES
Oven I/O performing inconsistently at high data speeds.	Programs fail after oven OS update	NO	YES (limited by receiver capability)



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Method | Traditional v/s Need

Traditional Method

Vendor diagnostics	Verify equipment performance to specification
Identify a pilot 'qualification' device	Stress limits of key specifications
Perform correlation exercise on pilot device	Baseline data can be from bench or an already qualified test system

RTP or Learning Cycle (LC)

Gaps in Current Method

Vendor diagnostics	Insufficient for all use cases. How do we fill this gap?
Identify diagnostic gaps related to user needs	What drives or limits performance? Identify corners, performance extents
Identify performance validation (PV) methods for each aspect of integration	Develop application(s) that utilizes system to test the identified diag gaps.
Develop and execute validation plan using PV methods above	Real-time tracking of issues and lessons learned. Vendor collaboration problem solving

Review the results and complete verification or LC



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Application Validation Example | Burn-In Systems

Identify composition of the complete test system

Define Test Plan and Develop application(s) that utilizes system to test the identified diag gaps

Application Board Capabilities:

- Measure supplies
 - Fully calibrated by an external meter
 - Test full ranges to specification & generate logs
- Load supplies
 - Tests maximum power of all supplies
- Test I/O channels
- Test airflow rate
- Test temperature
 - Verifies oven controller accuracy
- Design customizable to perform tests under different conditions for new hardware checkout

Power
Supplies

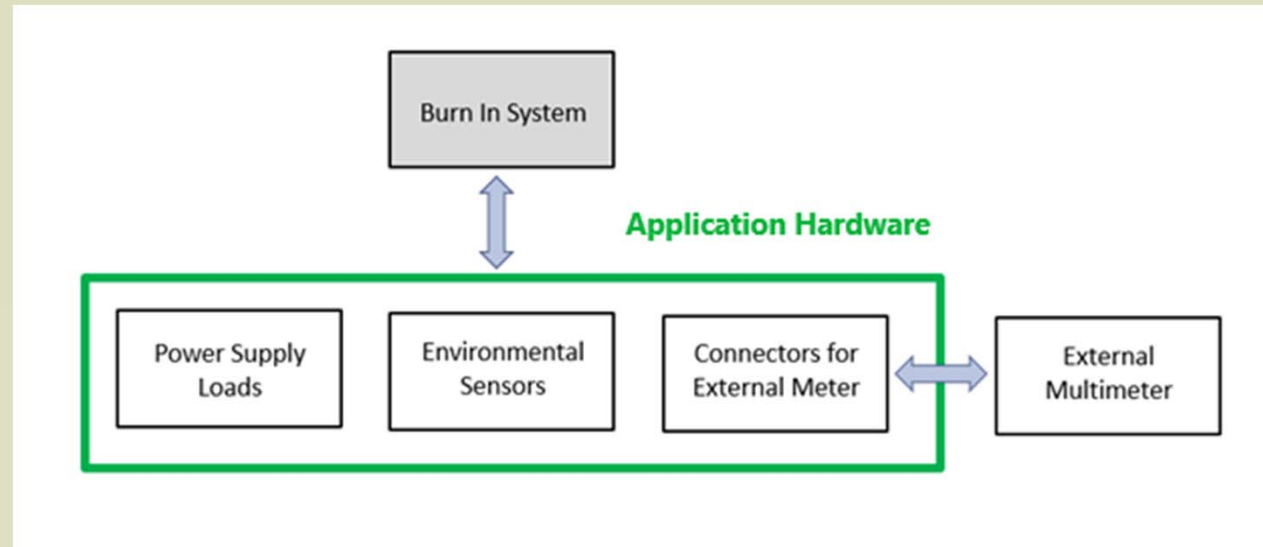
Relay
Switch

Temp
Controller

I/O
Channels

Composition of
New BI Oven

Test System Block Diagram



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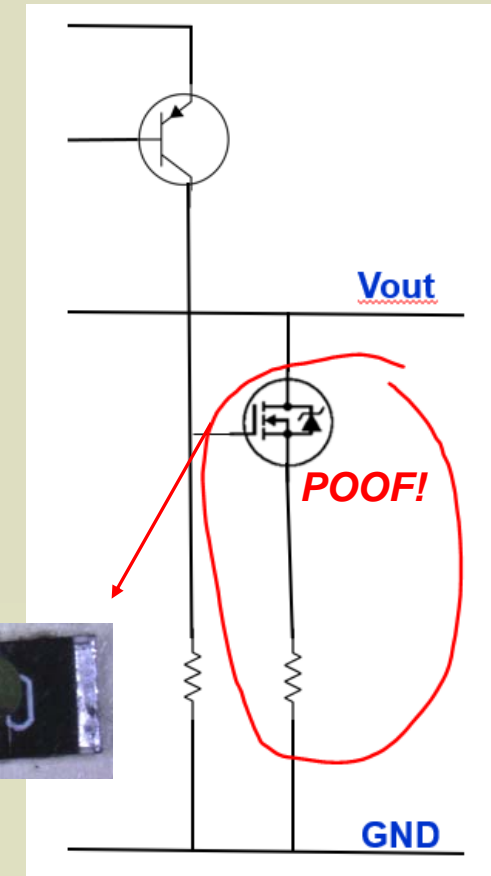
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Findings | Roadmap Burn-In System Deployment

Review the results and complete verification or LC

- Issue identified with Application Diagnostic and not identified by Vendor Diagnostic
 - Insufficient power supply discharge circuitry power handling **at higher voltage end of range**
 - Power supply **slew slower than previous generation hardware**
- Result
 - Testing was continued with an **improved discharge circuit revised by the vendor** with only minor delays
 - Understanding of slew range prevented extensive program rewrites and an update of the specification



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Impact | Roadmap Burn-In System Deployment

- Application diagnostics lead to 3 vendor learning cycles (LC)
 - 11 co-dependent changes pre-release
 - Two pilot products (traditional method) showed **no findings** with Rev A power supply (PS)
- Changes were made to
 - Supply circuit: Higher dissipation
 - Supply-to-supply and supply-to-ground short circuit protection : More Robust
 - Firmware (FW) : Better Monitoring
 - User Interface Software (SW): Updated
 - Specification change : Maximum allowable power supply capacitor

Vendor Deliverable	<div>LC1 : Vendor implements FW only fix</div> <div>LC2 : Vendor implements HW only fix</div> <div>LC3 : Vendor Implements HW+FW fix</div> <div>Scalability across existing fleet</div>				
	PS Rev A, Adapter A Rev A	PS Rev A, Adapter A Rev A, SW, FW Update	PS Rev B, Adapter A Rev B	PS Rev B, Adapter A Rev B, SW, FW Update	PS Rev B, Adapter H SW, FW Update
Application Diagnostic	Gen3	Gen3	Gen3	Gen3	Gen2 Backward Compatibility
Pilot H					
Pilot A					

Traditional Method 'Pass'

Improved Release

Legend

Failure

Pass

N/A



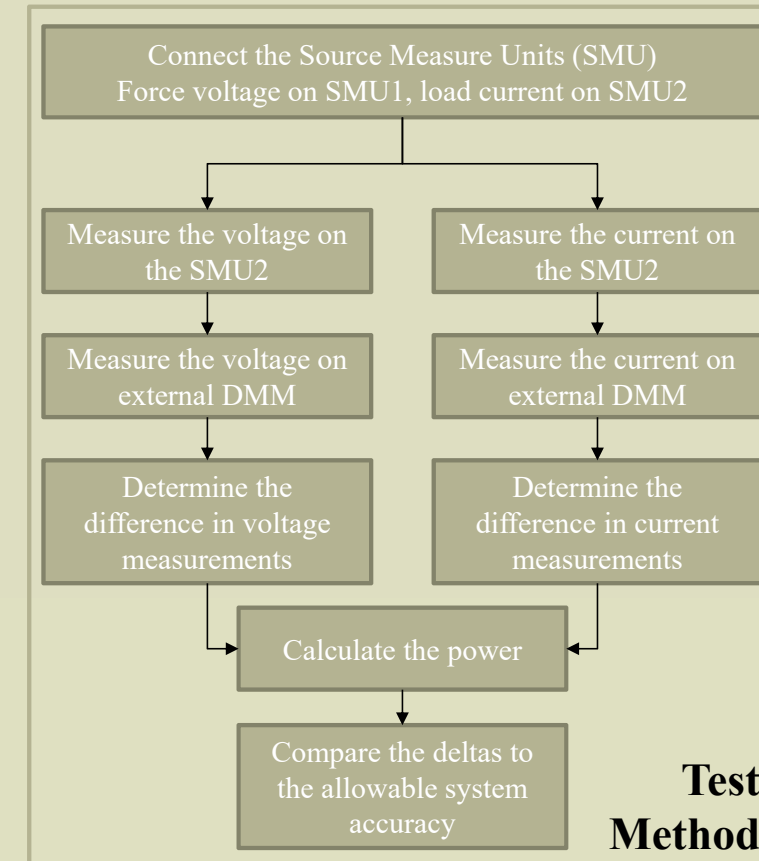
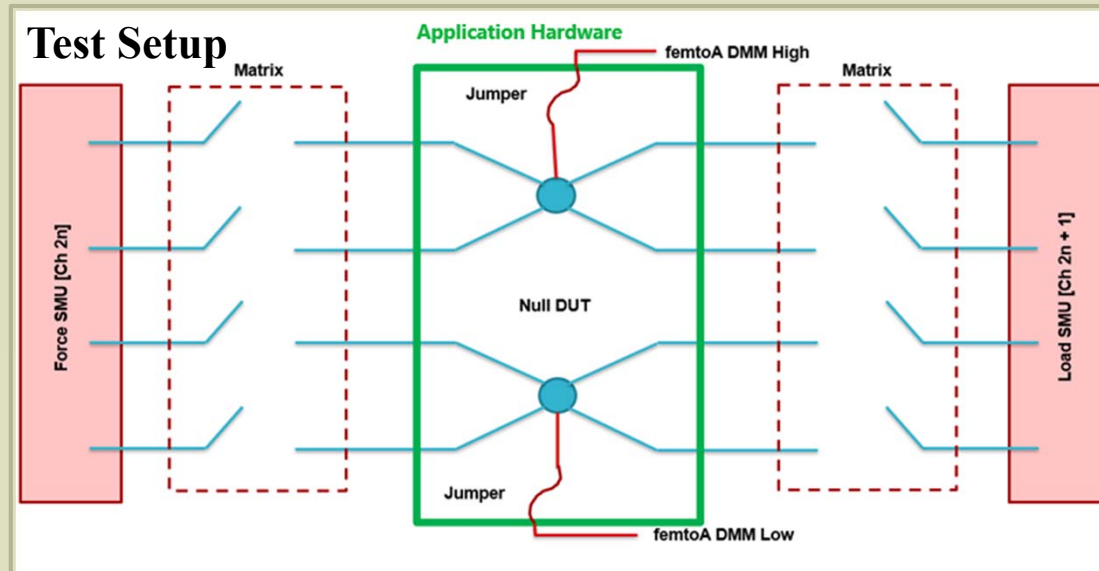
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Application Diagnostic Technique Reuse | Tester

- Validation plan for the roadmap tester
- Uses a combination of all known methods
 - Adds **NIST traceable** cross calibration & very low leakage noise floor checks
 - Application Diag tests power supply voltage, current, & power max's



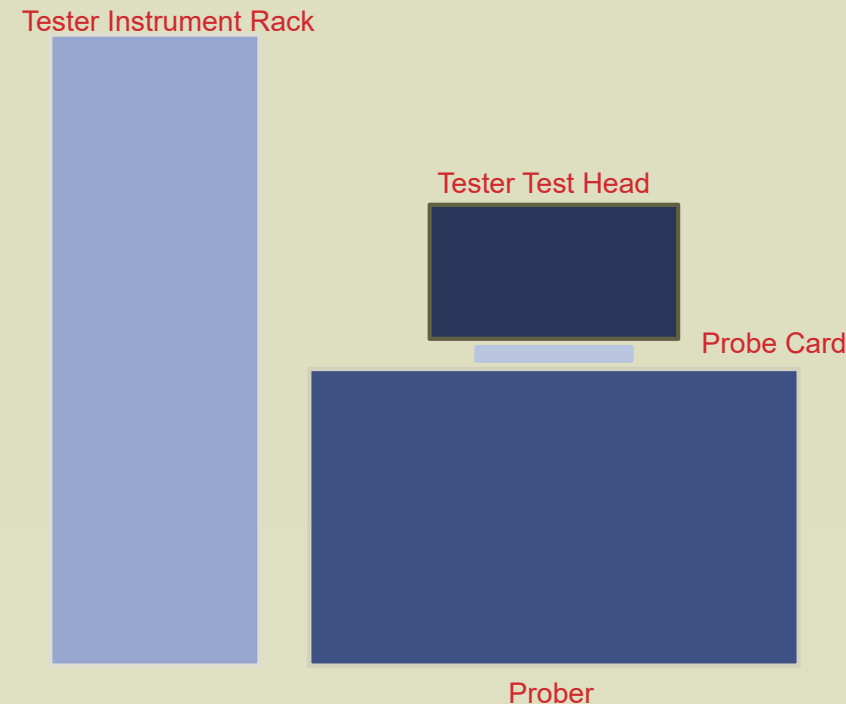
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Application Validation Evolution | Test Cell Noise Floor

- Test procedure for leakage (Noise Floor) **validation of entire Parametric Test Cell** as opposed to just the resources
- **NIST traceable** sub-femtoamp meter to be used to provide the range & accuracy needed to validate the system noise floor
- Includes **lessons learned** from past parametric validations
- Probe card noise may be measured separately and then deducted from the measured test cell noise



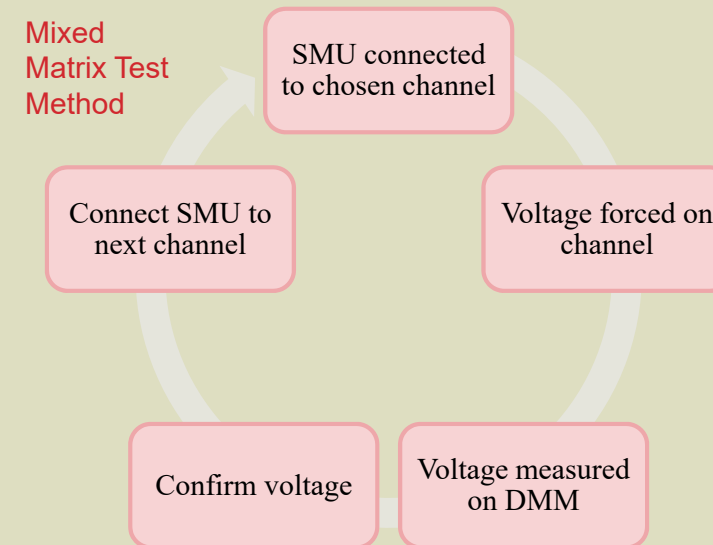
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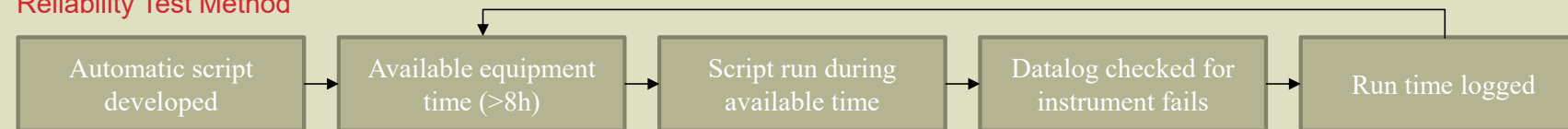
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Application Technique Reuse | Tester Matrix Reliability

- Validation plan for the relay matrix is broken into two tests
 - Mixed matrix test of all matrix combinations
 - Reliability test to check performance of matrix over time
 - Technique includes lessons learned from burn in validation



Reliability Test Method



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Application Diagnostic Benefits Summary

- Test system hardware and software **issues** identified and **corrected prior** to device **ramp** at vendor's expense.
- Application Diagnostic is **independent of device** performance.
- **Replacement of roadmap** tester(s) is **easier** due to test cell performance understanding.
- **Application Diagnostic** leverages **lessons learned** and includes **NIST** traceability, **Reliability** performance, and **Safety** adherence.
- Provides **vendor** with **Diagnostic gaps** understanding.



Credit: Bill Watterson



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Conclusion | How to Standardize

- The more comprehensive validation delivers **higher quality** production test systems while also **saving** both **time and money**.
- Can we **Standardize** better Validation techniques for **acceptance** and Roadmap **implementation** across the Tester Industry?

Advantage	Time Saved	Money Saved
Identifying and correcting infrastructure problems prior to system acceptance and release to factories	✓	✓
Validation hardware can be reused to perform acceptance testing on all future systems in the fleet	✓	✓
Standardizing the validation process for test infrastructure	✓	
Validate test cell integration and all capabilities of the system and subcomponents not limited to pilot devices		✓



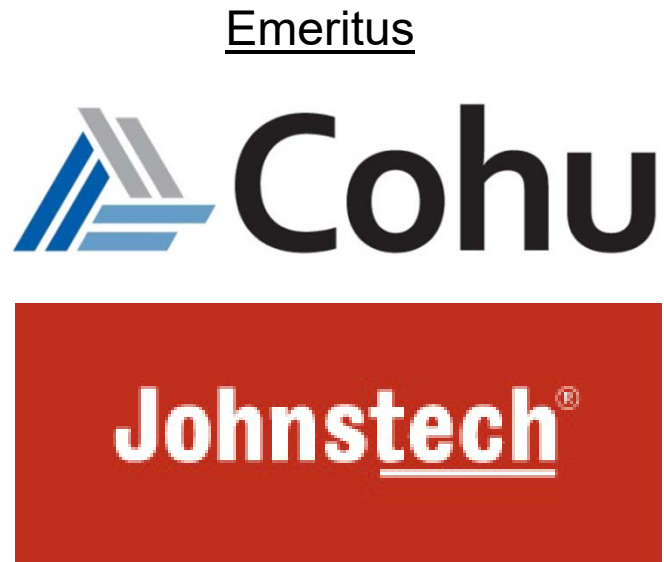
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